



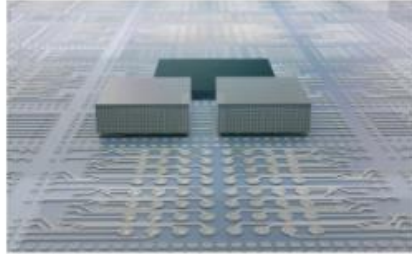
EV Group and Dymek Company Form Joint Venture Company in Malaysia to Enhance Regional Customer Support – May 26, 2023



Sustainability 101: It's Not Just Carbon - Reducing Greenhouse Gasses

The idea of semiconductor manufacturing becoming a trillion-dollar industry is astounding, exciting, or worrisome, depending on your viewpoint. Growth in the sector will provide jobs and create products that will make life better for millions of people. But the more chips we make, the higher the environmental impact of their manufacture due, in part, to the use of greenhouse gasses (GHG). Reducing GHG emissions per chip by 30% is helpful, but if you produce twice as many chips, the net result is increased emissions.

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Member of the Week



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[EV Group and Dymek Company Form Joint Venture Company in Malaysia to Enhance Regional Customer Support](#)

[TechSearch International Releases Market Forecast for BGAs and CSPs](#)

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Job Openings

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[Sr. Accountant, Global Accounting – Amkor](#)

[Marketing Communications Graphics Specialist – Amkor](#)

Events Calendar

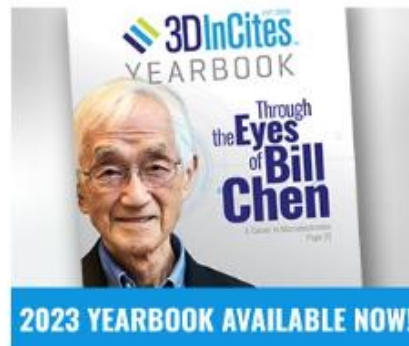
[MEMS World Summit 2023 – Europe](#)
June 13, 2023

[Workshop on Onshoring Advanced Packaging and Assembly](#)
July 10-12, 2023

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